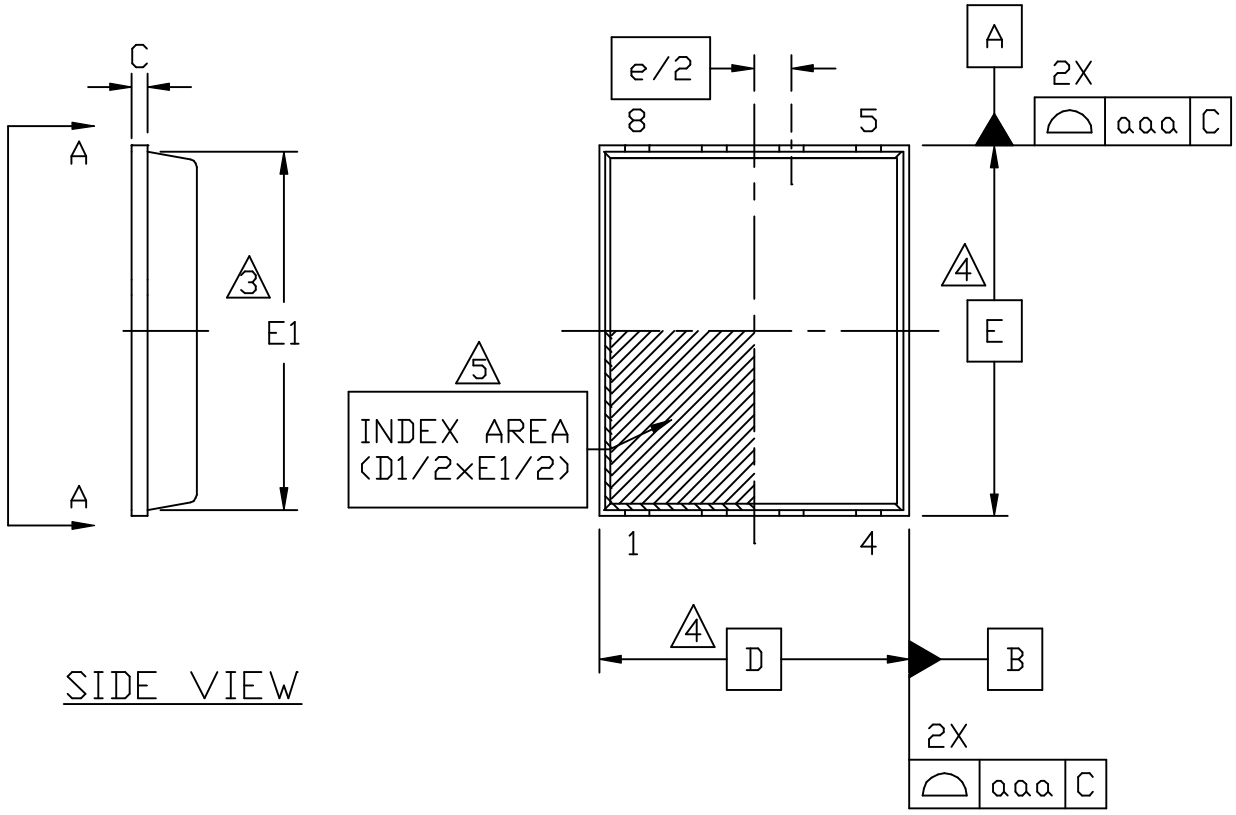
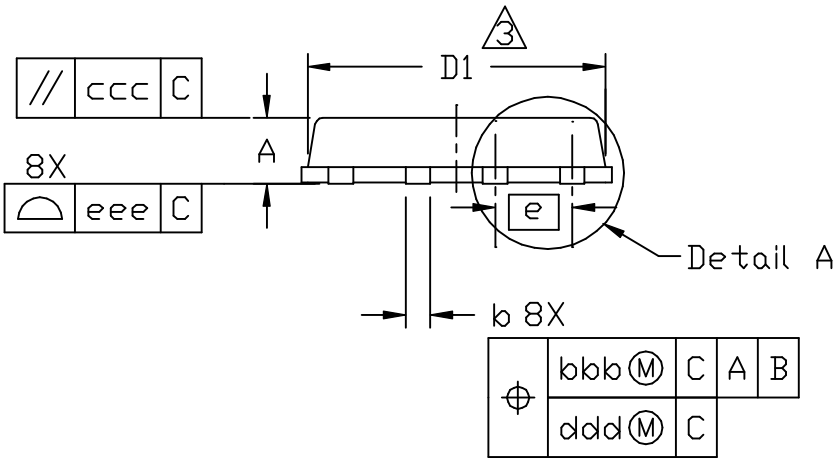


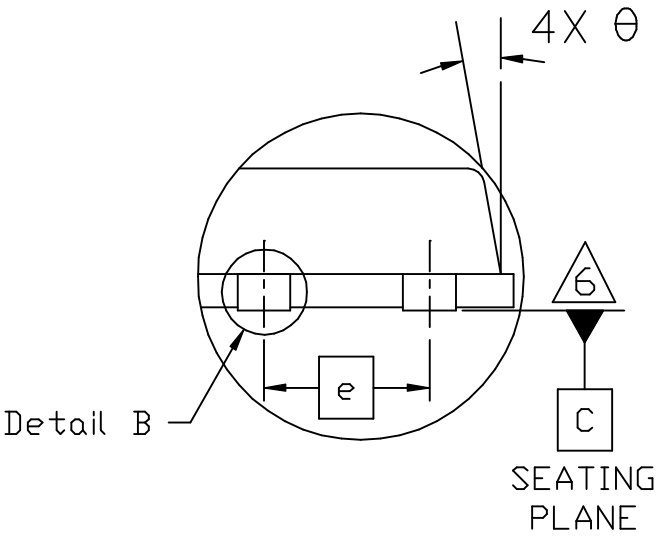
SIDE VIEW

TOP VIEW

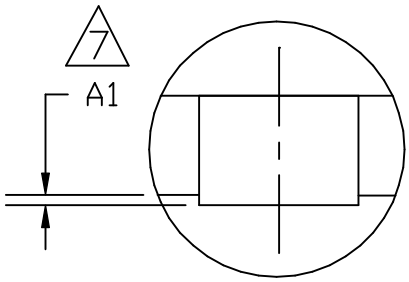


FRONT VIEW

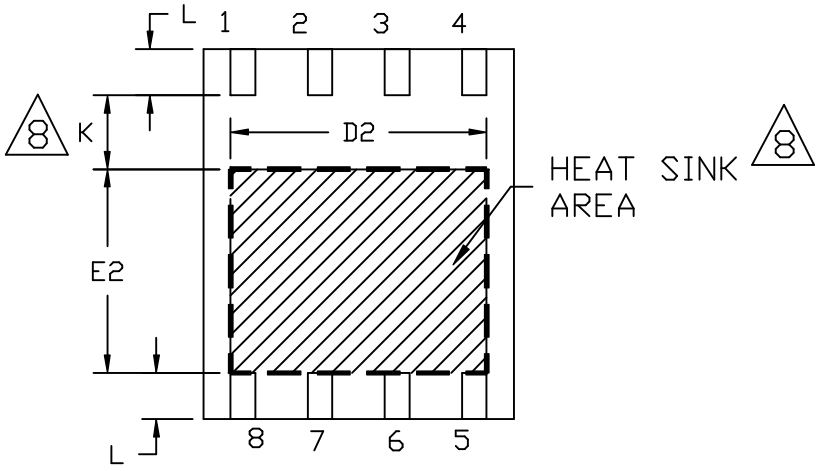
JEDEC SOLID STATE PRODUCT OUTLINE	THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.				
TITLE THERMALLY ENHANCED 8 LEAD, 1.27&0.65MM PITCH, LOW PROFILE PLASTIC DUAL FLAT, NO LEAD PACKAGE FAMILY	PACKAGE DESIGNATOR HL-PDFP-N	ISSUE A	DATE 10/02	MO-240	SHEET 1 OF 4



DETAIL A



DETAIL B



BACKSIDE VIEW OF PAD

VIEW A-A

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE THERMALLY ENHANCED 8 LEAD, 1.27&0.65MM PITCH, LOW PROFILE PLASTIC DUAL FLAT, NO LEAD PACKAGE FAMILY	ISSUE A	DATE 10/02	MO-240	SHEET 2 OF 4

VARIATIONS

AA				
Symbol	MIN	NOM	MAX	NOTES
A	0.90	1.05	1.20	
A1	0	——	0.05	
b	0.33	0.41	0.51	
c	0.23	0.28	0.33	
D	——	5.15BSC	——	4
D1	4.50	4.90	5.10	3
D2	0	——	4.22	8
E	——	6.15BSC	——	4
E1	5.50	5.80	6.10	3
E2	0	——	4.30	8
e	——	1.27BSC	——	
K	0.20	——	——	8
L	0.51	0.61	0.71	
θ	0°	——	12°	

TOLERANCE OF FORM AND POSITION	
aaa	0.20
bbb	0.10
ccc	0.10
ddd	0.05
eee	0.10
Notes	1,2
Ref	10-410
Issue	A

BA				
Symbol	MIN	NOM	MAX	NOTES
A	0.90	1.05	1.20	
A1	0	——	0.05	
b	0.23	0.30	0.40	
c	0.23	0.28	0.33	
D	——	3.30BSC	——	4
D1	2.70	3.05	3.20	3
D2	0	——	2.45	8
E	——	3.30BSC	——	4
E1	2.65	2.90	3.20	3
E2	0	——	1.90	8
e	——	0.65BSC	——	
K	0.20	——	——	8
L	0.30	0.43	0.56	
θ	0°	——	12°	

TOLERANCE OF FORM AND POSITION	
aaa	0.20
bbb	0.10
ccc	0.10
ddd	0.05
eee	0.10
Notes	1,2
Ref	10-410
Issue	A

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M-1994

2. All dimensions in millimeter

3. Dimensions D1 and E1 do not include mold flash protrusions or gate burrs.

4. Dimensions D and E include interterminal flash or protrusion. Interterminal flash or protrusion shall not exceed 0.25 mm per side

5. A visual index feature must be located within the hatched area

6. Seating plane is defined by terminal tips only

7. A1 is defined as the distance from the seating plane to the lowest point on package body

8. Size and shape of the heat sink is optional, but there should be a minimum distance K=0.20 mm between heat sink and leads and between two separate heat sinks. E2(max.) should not exceed (E-K-2L).
   Land pattern design should refer to individual actual package outline.

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE THERMALLY ENHANCED 8 LEAD, 1.27&0.65MM PITCH, LOW PROFILE PLASTIC DUAL FLAT, NO LEAD PACKAGE FAMILY	ISSUE A	DATE 10/02	MO-240	SHEET 4 OF 4